

Title (en)

METHOD AND DEVICE FOR DETERMINING CUTTING PARAMETERS FOR A LASER CUTTING MACHINE

Title (de)

VERFAHREN UND VORRICHTUNG ZUM ERMITTTELN VON SCHNEIDPARAMETERN FÜR EINE LASERSCHNEIDMASCHINE

Title (fr)

PROCÉDÉ ET DISPOSITIF DE DÉTERMINATION DE PARAMÈTRES DE COUPE D'UNE MACHINE DE COUPE AU LASER

Publication

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Application

**EP 20829775 A 20201218**

Priority

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Abstract (en)

[origin: WO2021123216A1] The invention relates to a method for determining cutting parameters for a laser cutting machine (18), having the steps of A) receiving at least one machine parameter, at least one process parameter and/or at least one material parameter; B) outputting properties, able to be influenced by the cutting parameters, of a laser cutting edge able to be cut by the laser cutting machine (18); C) receiving a weighting of the properties; D) determining the cutting parameters by using the at least one machine parameter, the at least one process parameter and/or the at least one material parameter and by using the weighted properties. The invention furthermore relates to a device for carrying out the method, in particular a device for machining a workpiece and/or a device that is designed to simulate a production process.

IPC 8 full level

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